

## Product Change Notice



**PCN:** PCN\_KVR16LE11\_8I\_C2

**Date:** October 30, 2014

**Kingston Technology Company**  
17600 Newhope Street  
Fountain Valley, CA 92708  
USA

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**Product Description:** 8GB DDR3L-1600 ECC Unbuffered DIMM CL11 2Rx8 1.35V Intel Certified

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**Product Affected:** KVR16LE11/8I

**Qualified Build:** 9965525-111.A00LF (Hynix A Die) – PHASE OUT

**Qualified Build:** 9965525-118.A00LF (Kingston F Die) – SHIPPING

**Qualified Build:** 996xxx-xxx.A00LF (Hynix B Die) – QUAL IN PROCESS

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**Type of Change:** Build (BOM) Phase Out Notification

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**Change Description:** Build 9965525-111.A00LF using Hynix A Die (H5TC4G83AFR-PBA) on 29nm process is being phased out. Alternate build 9965525-118.A00LF using Kingston F Die available. Replacement Hynix B Die on new 25nm process has been submitted for Intel qualification, estimated for December release.

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**Phase Out Notice:** October 30, 2014

**Target End of Life Date:** January 5, 2015

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